

GENERAL PURPOSE 5 V 100 MHz AGC AMPLIFIER

DESCRIPTION

The μPC3234GV is a silicon monolithic IC designed for use as AGC amplifier for digital CATV, cable modem and digital terrestrial systems. This IC consists of gain control amplifier and video amplifier.

The package is 8-pin SSOP (Shrink Small Outline Package) suitable for surface mount.

This IC is manufactured using our 30 GHz f_{max} UHS0 (Ultra High Speed Process) silicon bipolar process. This process uses silicon nitride passivation film. This material can protect chip surface from external pollution and prevent corrosion/migration. Thus, this IC has excellent performance, uniformity and reliability.

FEATURES

- Low distortion : $IM_3 = 54.0$ dBc TYP. @ single-ended output, $V_{out} = 105$ dBμV (0.5 V_{p-p}) /tone, $P_{in} = -30$ dBm/tone
- Low noise figure : NF = 4.0 dB TYP. @ maximum gain
- Wide AGC dynamic range : $GCR_{in} = 58.5$ dB TYP. @ input prescribe
- High ESD protection
- Packaged in 8-pin SSOP suitable for surface mounting

APPLICATIONS

- Digital terrestrial TV
- Digital CATV
- Cable modem receivers
- USB card

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPC3234GV-E1	μPC3234GV-E1-A	8-pin plastic SSOP (4.45 mm (175)) (Pb-Free)	3234	<ul style="list-style-type: none"> • Embossed tape 8 mm wide • Pin 1 indicates pull-out direction of tape • Qty 1 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

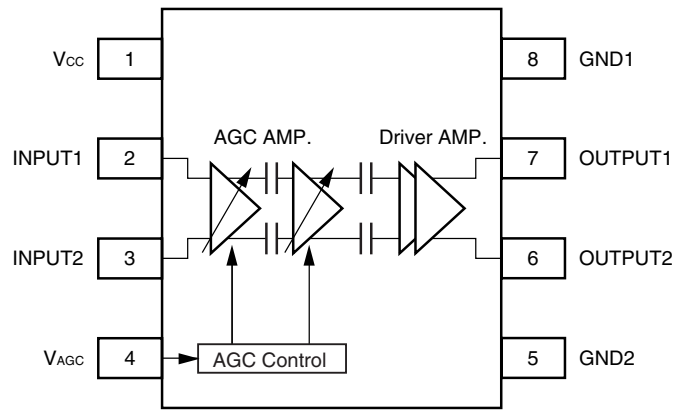
Part number for sample order: μPC3234GV

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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INTERNAL BLOCK DIAGRAM AND PIN CONNECTIONS

(Top View)



PIN EXPLANATIONS

Pin No.	Pin Name	Applied Voltage (V)	Pin Voltage (V) ^{Note}	Function and Application	Internal Equivalent Circuit
1	V _{CC}	4.5 to 5.5	—	Power supply pin. This pin should be externally equipped with bypass capacitor to minimize ground impedance.	
2	INPUT1	—	1.2	Signal input pins to AGC amplifier. This pin should be coupled with capacitor for DC cut.	
3	INPUT2	—	1.2		
4	V _{AGC}	0 to V _{CC}	—	Gain control pin. This pin's bias govern the AGC output level. Minimum Gain at V _{AGC} : 0 to 0.4 V Maximum Gain at V _{AGC} : 3.0 to 3.5 V Recommended to use AGC voltage with externally resistor (example: 1 kΩ).	
5	GND2	0	—	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible.	
6	OUTPUT2	—	2.4	Signal output pins of video amplifier. This pin should be coupled with capacitor for DC cut.	
7	OUTPUT1	—	2.4		
8	GND1	0	—	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All ground pins must be connected together with wide ground pattern to decrease impedance difference.	

Note Pin voltage is measured at V_{CC} = 5.0 V.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	V _{CC}	T _A = +25°C	6.0	V
Gain Control Voltage Range	V _{AGC}	T _A = +25°C	0 to V _{CC}	V
Power Dissipation	P _D	T _A = +85°C Note	250	mW
Operating Ambient Temperature	T _A		-40 to +85	°C
Storage Temperature	T _{stg}		-55 to +150	°C

Note Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{CC}		4.5	5.0	5.5	V
Operating Ambient Temperature	T _A	V _{CC} = 4.5 to 5.5 V	-40	+25	+85	°C
Gain Control Voltage Range	V _{AGC}		0	-	3.5	V
Operating Frequency Range	f _{ew}		30	-	100	MHz

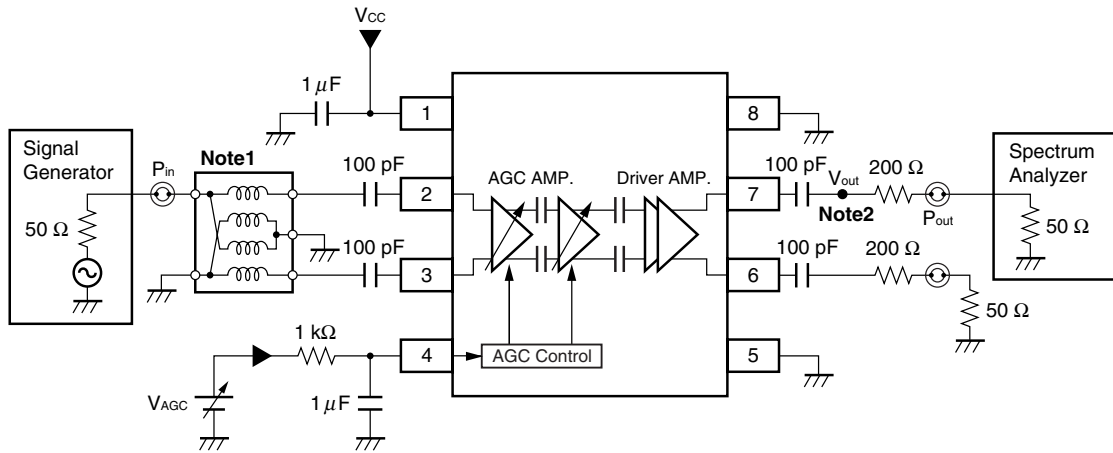
ELECTRICAL CHARACTERISTICS

(T_A = +25°C, V_{CC} = 5 V, f = 45 MHz, Z_s = 50 Ω, Z_L = 250 Ω, single-ended output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
DC Characteristics						
Circuit Current	I _{CC}	V _{CC} = 5 V, No input signal Note 1	–	28.5	38	mA
AGC Voltage High Level	V _{AGC (H)}	@ Maximum gain Note 1	3.0	–	3.5	V
AGC Voltage Low Level	V _{AGC (L)}	@ Minimum gain Note 1	0	–	0.4	V
RF Characteristics						
IF Input Frequency Range	f _{IFin}	f _c = –3 dB @ 45 MHz Note 1	30	–	100	MHz
Maximum Voltage Gain	G _{MAX}	V _{AGC} = 3.0 V, P _{in} = –60 dBm Note 1	60	63	66	dB
Minimum Voltage Gain	G _{MIN}	V _{AGC} = 0.4 V, P _{in} = –30 dBm Note 1	1.5	4.5	7.5	dB
Gain Control Range (input prescribe)	GCR _{in}	V _{AGC} = 0.4 to 3.0 V Note 1	52.5	58.5	–	dB
Output Voltage	V _{out}	P _{in} = –59 to –17 dBm Note 1	–	1.0	–	V _{p-p}
Maximum Output Voltage	V _{oclip}	V _{AGC} = 3.0 V Note 1	2.0	2.7	–	V _{p-p}
Noise Figure	NF	V _{AGC} = 3.0 V Note 2	–	4.0	5.5	dB
3rd Order Intermodulation Distortion	IM ₃	f ₁ = 44 MHz, f ₂ = 45 MHz, P _{in} = –30 dBm/tone, V _{out} = 105 dBμV (0.5 V _{p-p}) /tone Note 1	48	54	–	dBc
Input Impedance	Z _{in}	V _{AGC} = 0 V Note 3	–	0.7//2.8	–	kΩ/pF

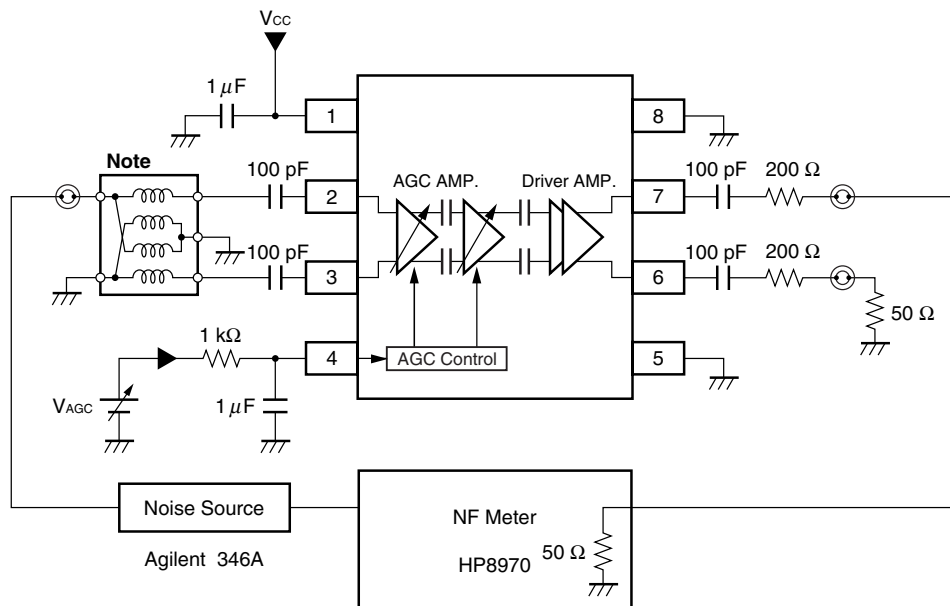
- Notes 1.** By measurement circuit 1
2. By measurement circuit 2
3. By measurement circuit 3

MEASUREMENT CIRCUIT 1



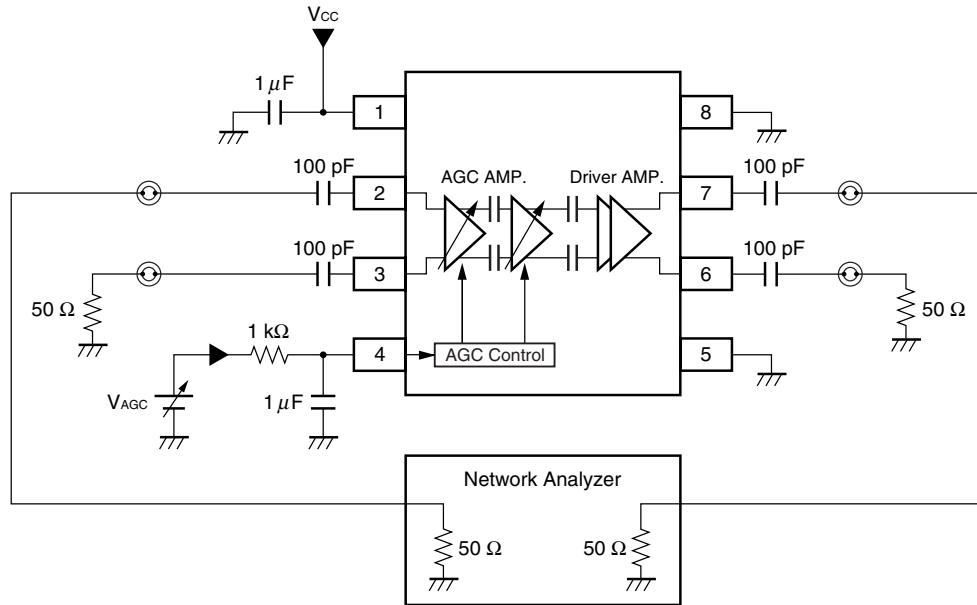
- Notes 1. Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)
- 2. $V_{out} \text{ (dBmV)} = P_{out} \text{ (dBm)} + 20 \log (250 \Omega / 50 \Omega) + 46.99$

MEASUREMENT CIRCUIT 2



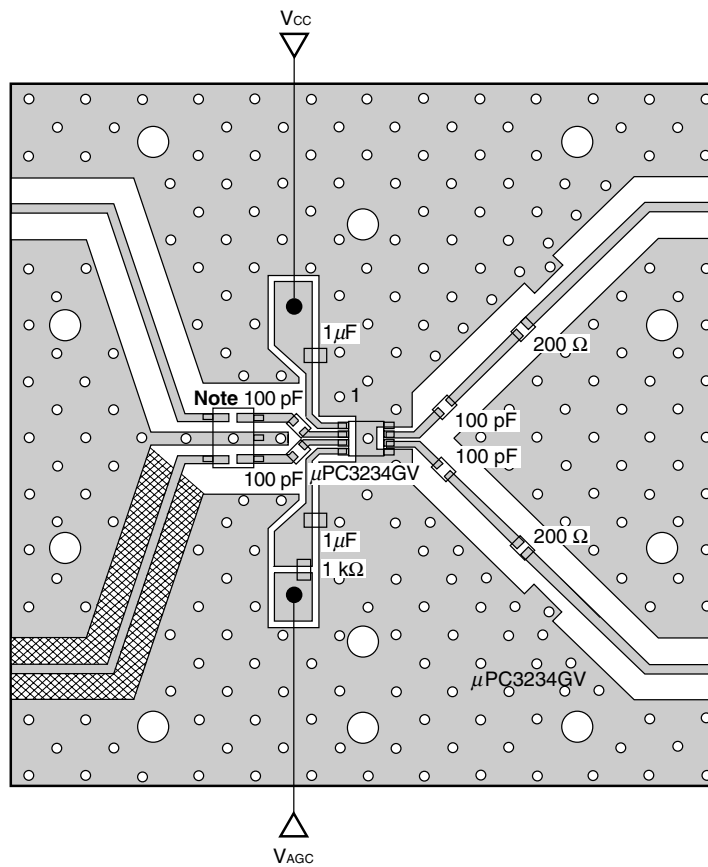
Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 3




The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD
(MEASUREMENT CIRCUIT 1)



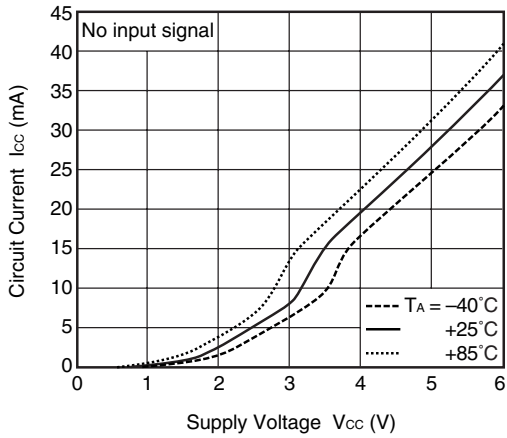
Note Balun Transformer

Remarks

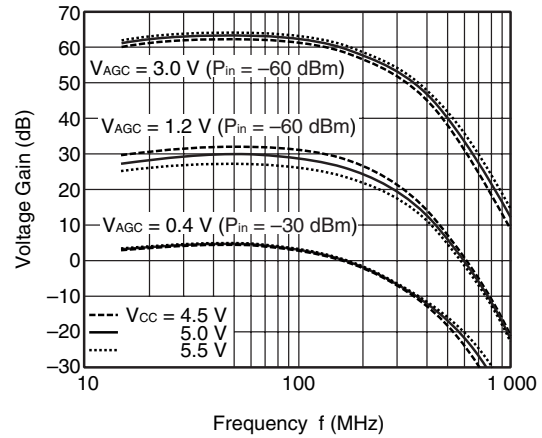
1. Back side: GND pattern
2. Au plated on pattern
3. ○: Through hole
4.  represents short-circuit strip

TYPICAL CHARACTERISTICS (T_A = +25°C , unless otherwise specified)

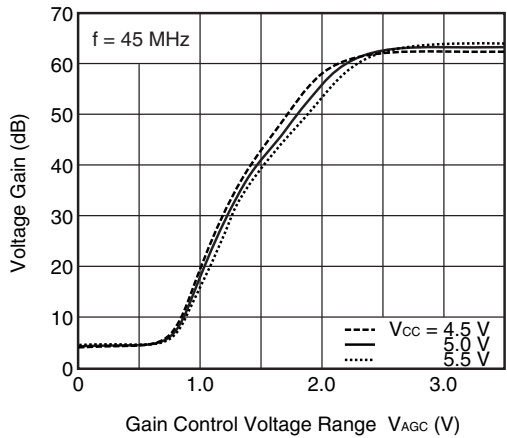
CIRCUIT CURRENT vs. SUPPLY VOLTAGE



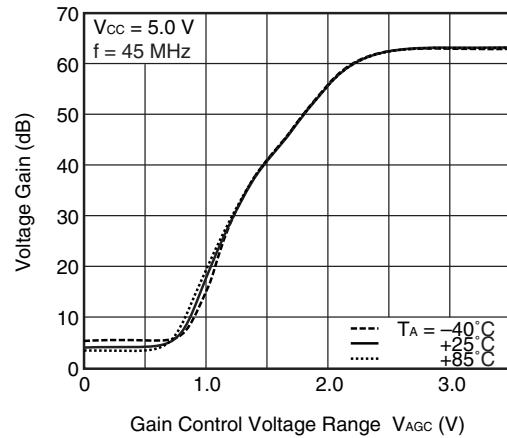
VOLTAGE GAIN vs. FREQUENCY



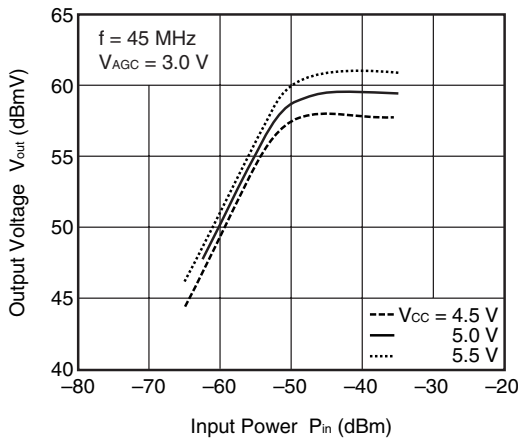
VOLTAGE GAIN vs. GAIN CONTROL VOLTAGE RANGE



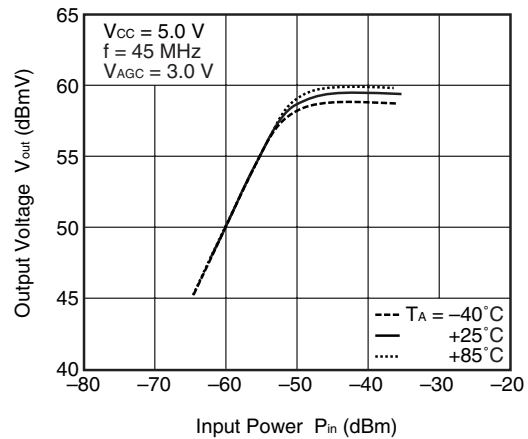
VOLTAGE GAIN vs. GAIN CONTROL VOLTAGE RANGE



OUTPUT VOLTAGE vs. INPUT POWER

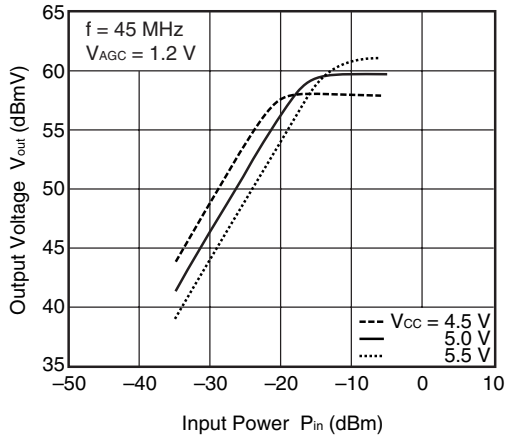


OUTPUT VOLTAGE vs. INPUT POWER

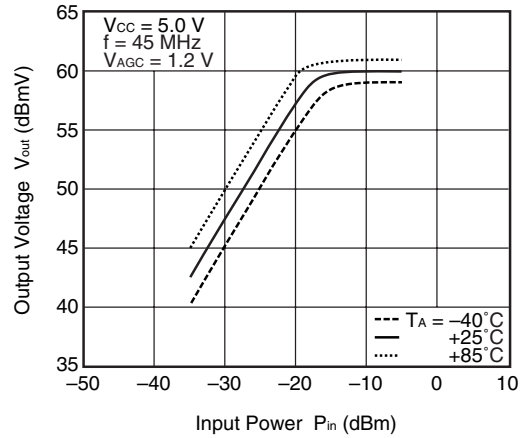


Remark The graphs indicate nominal characteristics.

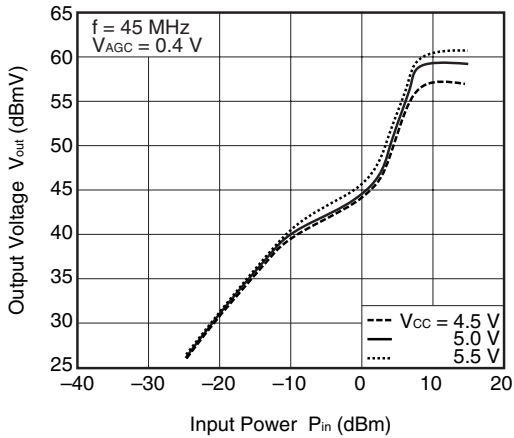
OUTPUT VOLTAGE vs. INPUT POWER



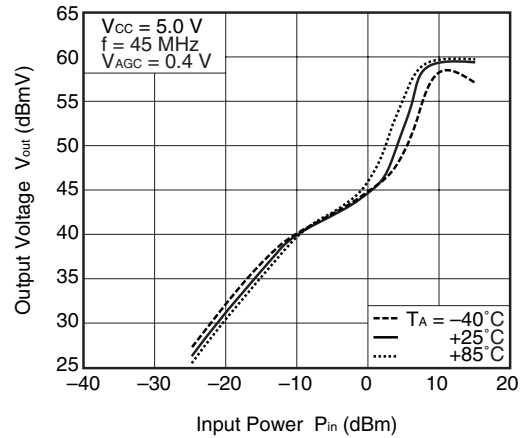
OUTPUT VOLTAGE vs. INPUT POWER



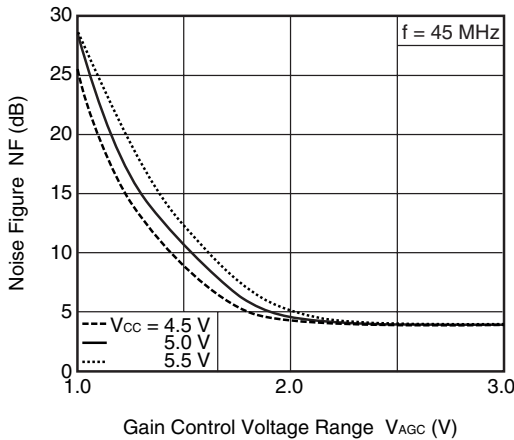
OUTPUT VOLTAGE vs. INPUT POWER



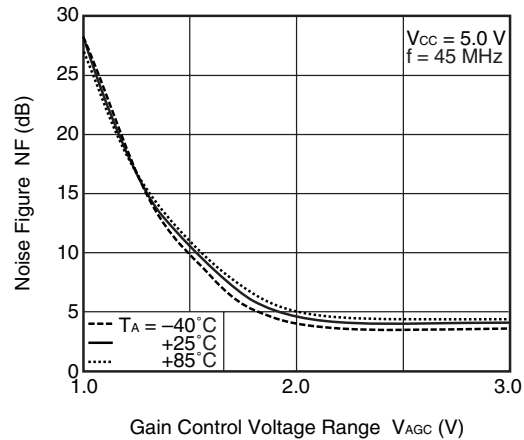
OUTPUT VOLTAGE vs. INPUT POWER



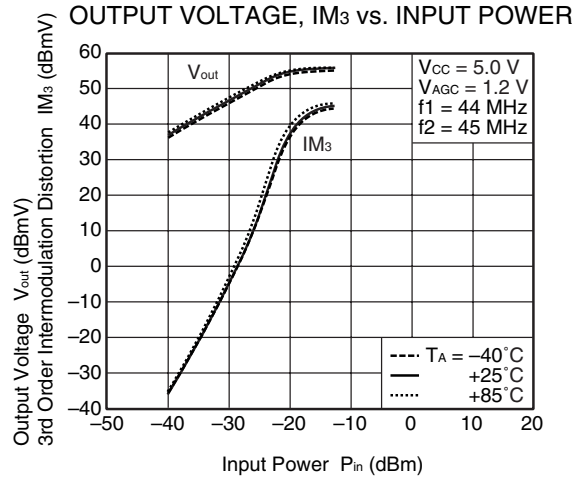
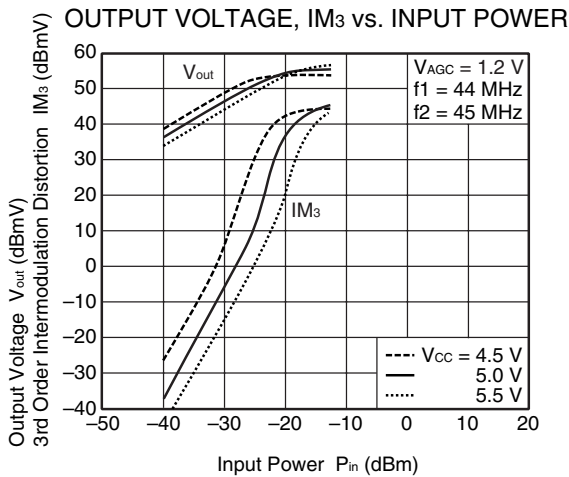
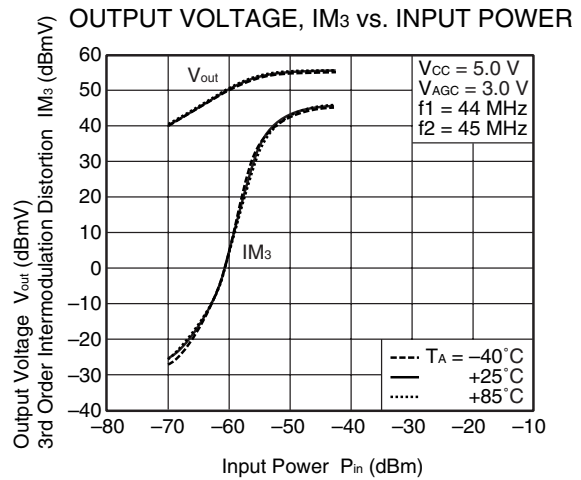
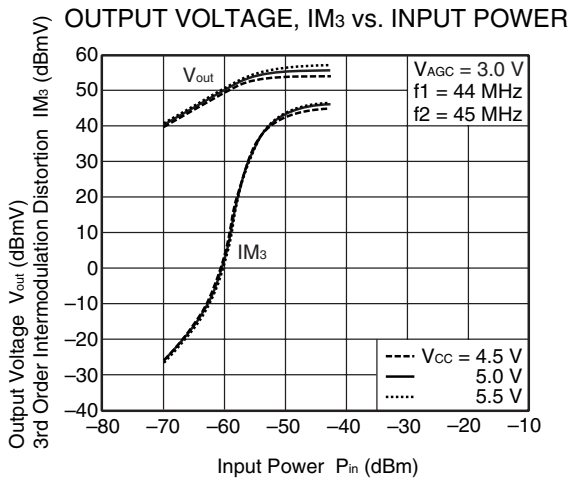
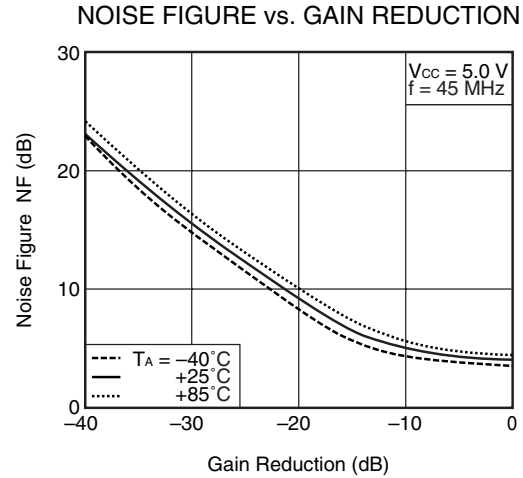
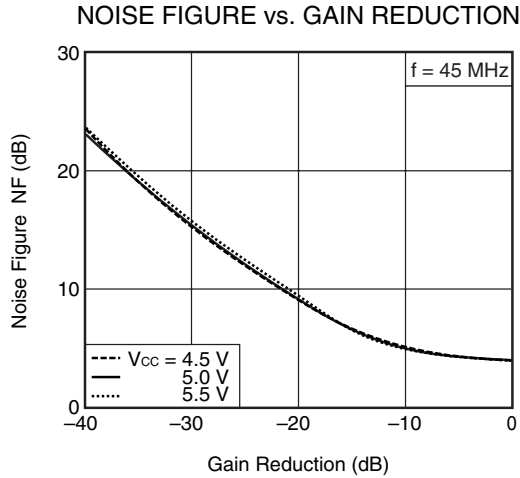
NOISE FIGURE vs. GAIN CONTROL VOLTAGE RANGE



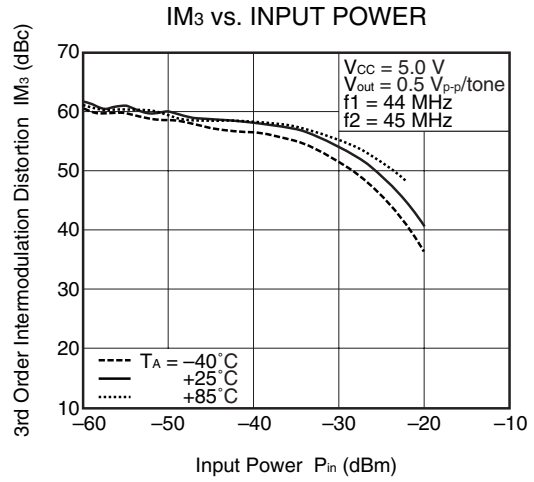
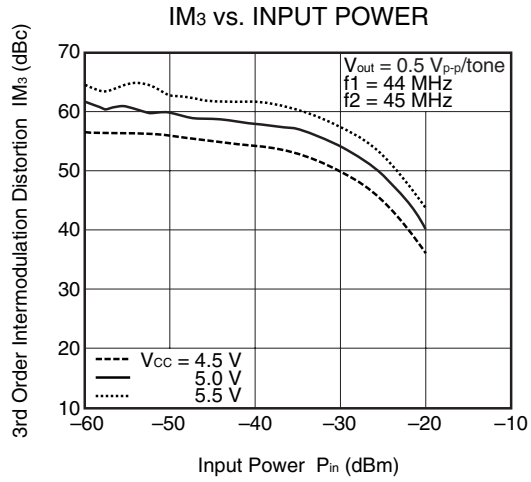
NOISE FIGURE vs. GAIN CONTROL VOLTAGE RANGE



Remark The graphs indicate nominal characteristics.



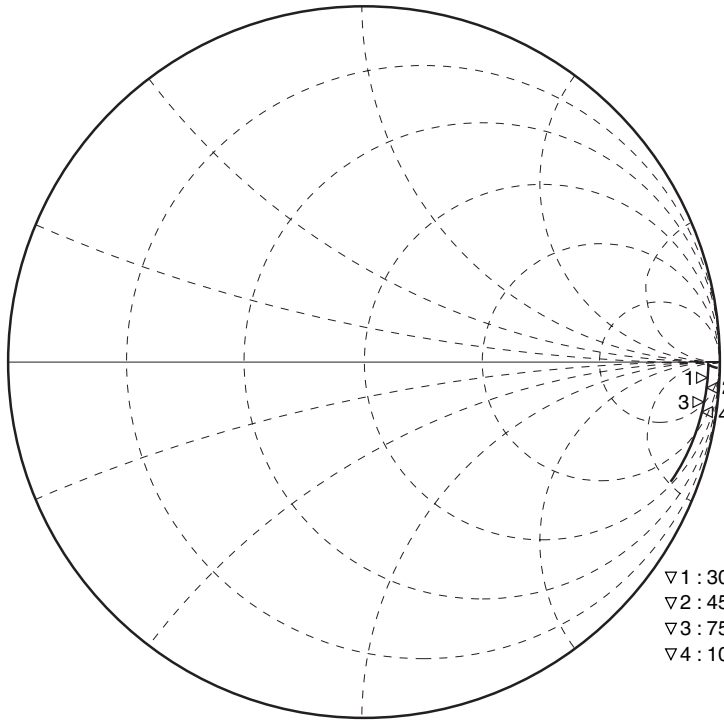
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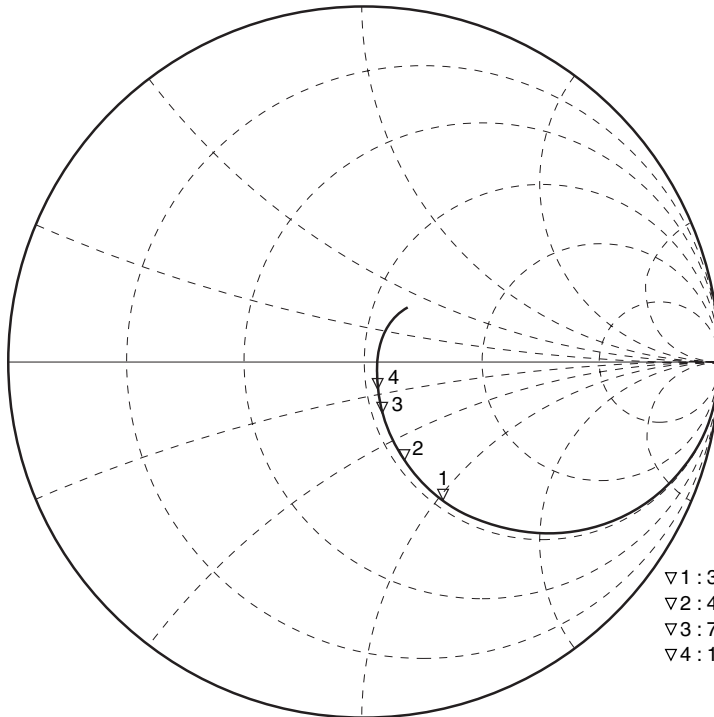
S-PARAMETERS ($T_A = +25^\circ\text{C}$, $V_{CC} = 5.0\text{ V}$, $V_{AGC} = 0\text{ V}$)

S₁₁-FREQUENCY



▽1 : 30 MHz	1.191 k Ω	-1.468 k Ω	3.614 pF
▽2 : 45 MHz	707.0 Ω	-1.248 k Ω	2.834 pF
▽3 : 75 MHz	340.1 Ω	-894.3 Ω	2.373 pF
▽4 : 100 MHz	215.7 Ω	-712.6 Ω	2.233 pF

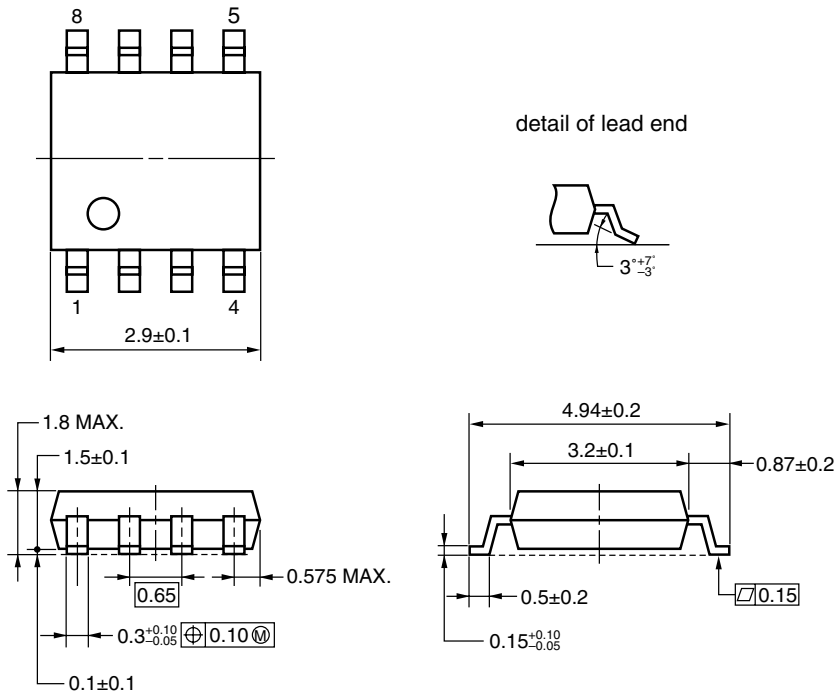
S₂₂-FREQUENCY



▽1 : 30 MHz	53.28 Ω	-51.66 Ω	102.7 pF
▽2 : 45 MHz	53.32 Ω	-32.47 Ω	108.9 pF
▽3 : 75 MHz	53.42 Ω	-15.82 Ω	134.1 pF
▽4 : 100 MHz	53.79 Ω	-8.586 Ω	185.4 pF

PACKAGE DIMENSIONS

8-PIN PLASTIC SSOP (4.45 mm (175)) (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below
	Time at peak temperature	: 10 seconds or less
	Time at temperature of 220°C or higher	: 60 seconds or less
	Preheating time at 120 to 180°C	: 120±30 seconds
	Maximum number of reflow processes	: 3 times
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below
Wave Soldering	Peak temperature (molten solder temperature)	: 260°C or below
	Time at peak temperature	: 10 seconds or less
	Preheating temperature (package surface temperature)	: 120°C or below
	Maximum number of flow processes	: 1 time
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below
	Soldering time (per side of device)	: 3 seconds or less
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below

Caution Do not use different soldering methods together (except for partial heating).

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